UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/709,428	05/05/2004	Cheng-Yen Huang	FTCP0035USA	3427	
27765 NORTH AME	27765 7590 06/18/2007 NORTH AMERICA INTELLECTUAL PROPERTY CORPORATION			EXAMINER	
P.O. BOX 506			TRINH, HOA B		
MERRIFIELD	, VA 22116		ART UNIT	PAPER NUMBER	
			2814		
			NOTIFICATION DATE	DELIVERY MODE	
•			06/18/2007	ELECTRONIC	

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

winstonhsu.uspto@gmail.com Patent.admin.uspto.Rcv@naipo.com mis.ap.uspto@naipo.com.tw

<u> </u>		TH			
	Application No.	Applicant(s)			
	10/709,428	HUANG, CHENG-YEN			
Office Action Summary	Examiner	Art Unit			
	Vikki H. Trinh	2814			
The MAILING DATE of this communica Period for Reply	tion appears on the cover sheet w	ith the correspondence address			
A SHORTENED STATUTORY PERIOD FOR WHICHEVER IS LONGER, FROM THE MAIL - Extensions of time may be available under the provisions of 3 after SIX (6) MONTHS from the mailing date of this communic - If NO period for reply is specified above, the maximum statuto - Failure to reply within the set or extended period for reply will, Any reply received by the Office later than three months after earned patent term adjustment. See 37 CFR 1.704(b).	LING DATE OF THIS COMMUNI 7 CFR 1.136(a). In no event, however, may a cation. by period will apply and will expire SIX (6) MOI by statute, cause the application to become A	CATION. reply be timely filed NTHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).			
Status					
1)⊠ Responsive to communication(s) filed of	on <u>08 May 2007</u> .				
2a) This action is FINAL . 2b)	This action is FINAL . 2b)⊠ This action is non-final.				
3) Since this application is in condition for closed in accordance with the practice	•	• •			
Disposition of Claims	•				
4) ⊠ Claim(s) 35-42 is/are pending in the ap 4a) Of the above claim(s) 36-42 is/are v 5) ☐ Claim(s) is/are allowed. 6) ⊠ Claim(s) 35 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction	vithdrawn from consideration.				
Application Papers					
9) The specification is objected to by the E	Examiner.				
10) The drawing(s) filed on is/are: a	•	-			
Applicant may not request that any objection	- · · ·	, ,			
Replacement drawing sheet(s) including the state of the s		- 1 1			
Priority under 35 U.S.C. § 119					
12) Acknowledgment is made of a claim for a) All b) Some * c) None of: 1. Certified copies of the priority do 2. Certified copies of the priority do 3. Copies of the certified copies of application from the Internationa * See the attached detailed Office action f	cuments have been received. cuments have been received in A the priority documents have beer I Bureau (PCT Rule 17.2(a)).	Application No n received in this National Stage			
Attachment(s)					
 Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PTO 3) Information Disclosure Statement(s) (PTO-1449 or PT Paper No(s)/Mail Date 	-948) Paper No	Summary (PTO-413) (s)/Mail Date Informal Patent Application (PTO-152) 			

Application/Control Number: 10/709,428 Page 2

Art Unit: 2814

DETAILED ACTION

Continued Examination Under 37 CFR 1.114

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 05/08/2007 has been entered.

Election/Restrictions

- 2. Restriction to one of the following inventions is required under 35 U.S.C. 121:
 - I. Claim 35 drawn to chip packaging device, classified in class 257, subclass 676.
- II. Claims 36-42, drawn to method, classified in class 438, subclass 15.

 The inventions are distinct, each from the other because of the following reasons:
- 3. Inventions I and II are related as process of making and product made. The inventions are distinct if either or both of the following can be shown: (1) that the process as claimed can be used to make another and materially different product or (2) that the product as claimed can be made by another and materially different process (MPEP § 806.05(f)). In the instant case, the product can be made with another materially different process that the process includes the step of attaching the bonding pad with adhesive.
- 4. Because these inventions are independent or distinct for the reasons given above and there would be a serious burden on the examiner if restriction is not required because the inventions have acquired a separate status in the art due to their recognized divergent subject matter, restriction for examination purposes as indicated is proper.

5. Newly submitted claims 36-42 are directed to an invention that is independent or distinct from the invention originally claimed for the following reasons: Claims 36 –37 are directed to method of making; In claim 38, the step of "providing a connection…enabling or disabling the functionality of the chip in different applications" was not presented in the original presentation; and similarity, the steps of claims 39-42 fall with claim 37.

Since applicant has received an action on the merits for the originally presented invention, this invention has been constructively elected by original presentation for prosecution on the merits. Accordingly, claims 37-42 withdrawn from consideration as being directed to a non-elected invention. See 37 CFR 1.142(b) and MPEP § 821.03.

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

 (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 2. Claim 35 is rejected under 35 U.S.C. 102(e) as being anticipated by Sutardja et al. (6,903,448) (hereinafter Sutardja).

As to claim 35, Sutardja discloses a packaging comprising a package substrate 1 (figure 7) connected inherently to either a high voltage or a low voltage for turning the

Art Unit: 2814

device on, a chip 2 (fig. 7) mounted on the package substrate and comprises a plurality of bonding option unit (col. 5, lines 47-48) that comprises a bonding pad (col. 5, lines 47-48); a plurality of first lead frame 72, 52 (fig. 7); the bonding pad of each bonding option unit has corresponding first lead frame 52, 72 (fig. 7) such that there exists a one-to-one correspondence between the bonding pads and the first lead frames; the first lead frame 52, 72 being connected to either a high voltage or a low voltage (note Vout), wherein the voltage level of the first lead frame 52 or 72 is inherently logical opposite of the voltage level of the substrate; wherein the bonding pad (col. 5, lines 47-48) of each bonding option unit is connected to the package substrate 1 or the corresponding first lead frame 52, 72 for providing two types of bonding options for each bonding option unit (fig. 7). Note that the bonding pad in a semiconductor chip device is used and determined for functioning purpose. (Note that Sutardja also reads on claims 36-37).

Response to Arguments

3. Applicant's arguments with respect to claims 35-42 have been considered but they are not persuasive.

Regarding to claim 35, applicants argue that the Sutardja does the teach the amended portion of the claims. However, in viewing the reference as a whole, Sutardja teaches all of the limitation of the claims. Note that the bonding pad which connects to the die and the lead also receives voltage values. Thus, applicants have not yet overcome the cited reference.

Regarding to claims 36-42, the examiner restricts the claims because the claims are distinct from the original presentation (dated filed 05/05/2004)

Application/Control Number: 10/709,428 Page 5

Art Unit: 2814

Conclusion

Any request for information regarding to the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Also, status information for published applications may be obtained from either Private PAIR or Public Pair. In addition, status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. If you have questions pertaining to the Private PAIR system, please contact the Electronic Business Center (EBC) at 866-217-9197 (toll free).

Lastly, paper copies of cited U.S. patents and U.S. patent application publications will cease to be mailed to applicants with Office actions as of June 2004. Paper copies of foreign patents and non-patent literature will continue to be included with office actions. These cited U.S. patents and patent application publications are available for download via the Office's PAIR. As an alternate source, all U.S. patents and patent application publications are available on the USPTO web site (www.uspto.gov), from the Office of Public Records and from commercial sources. Applicants are referred to the Electronic Business Center (EBC) at http://www.uspto.gov/ebc/index.html or 1-866-217-9197 for information on this policy. Requests to restart a period for response due to a missing U.S. patent or patent application publications will not be granted.

Vikki Trinh, Patent Examiner AU 2814

> "HOWARD WEISS PRIMARY EXAMINER